

SOT1653-2

FBGA780, fine-pitch ball grid array package, 780 terminals,
0.8 mm pitch, 23 mm x 23 mm x 2.46 mm body

8 March 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA780
Package style descriptive code	FBGA (fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	26-02-2019
Manufacturer package code	98ASA01409D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	23	-	mm
package width	-	23	-	mm
package height	-	2.46	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	780	-	



2 Package outline

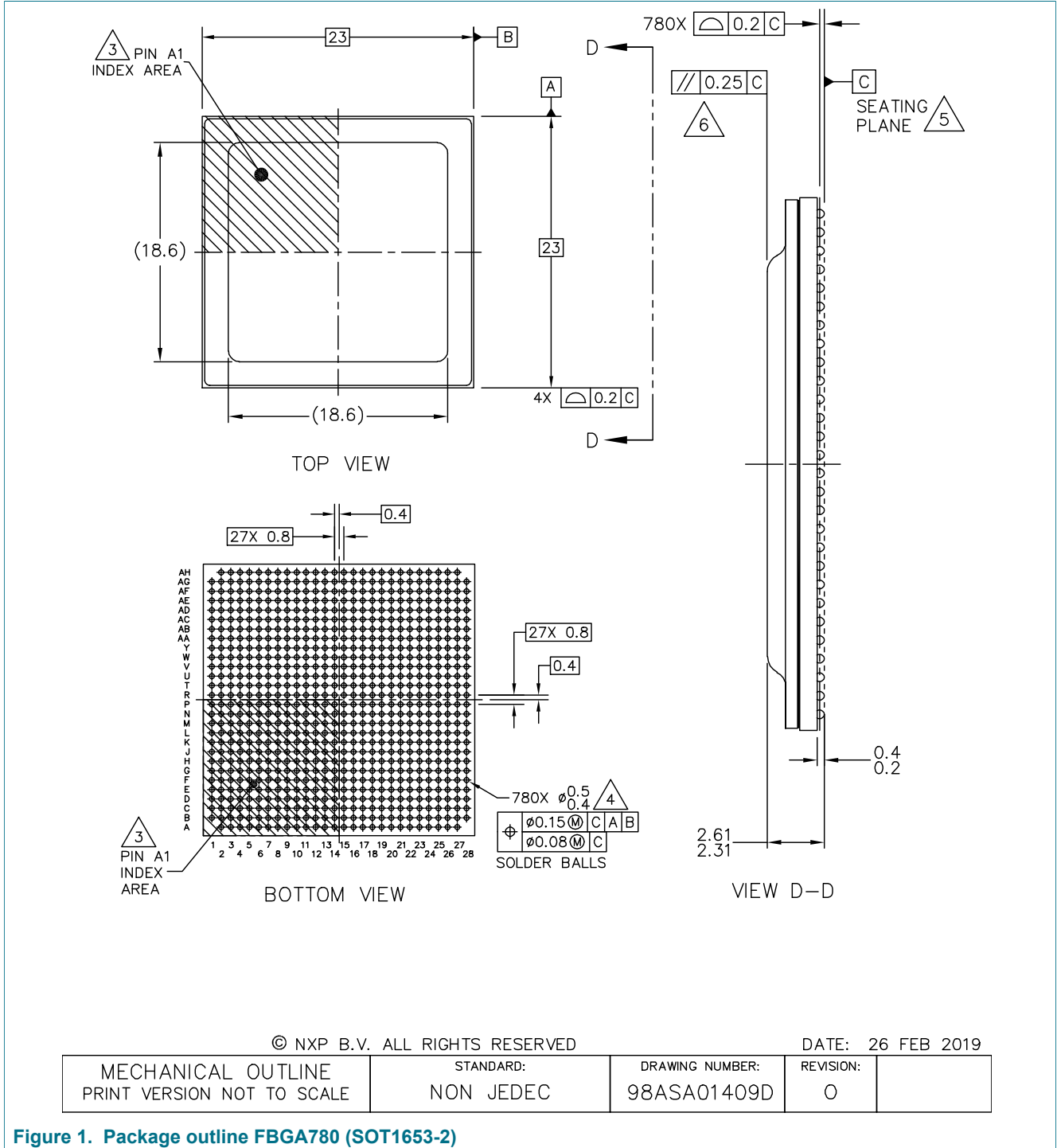
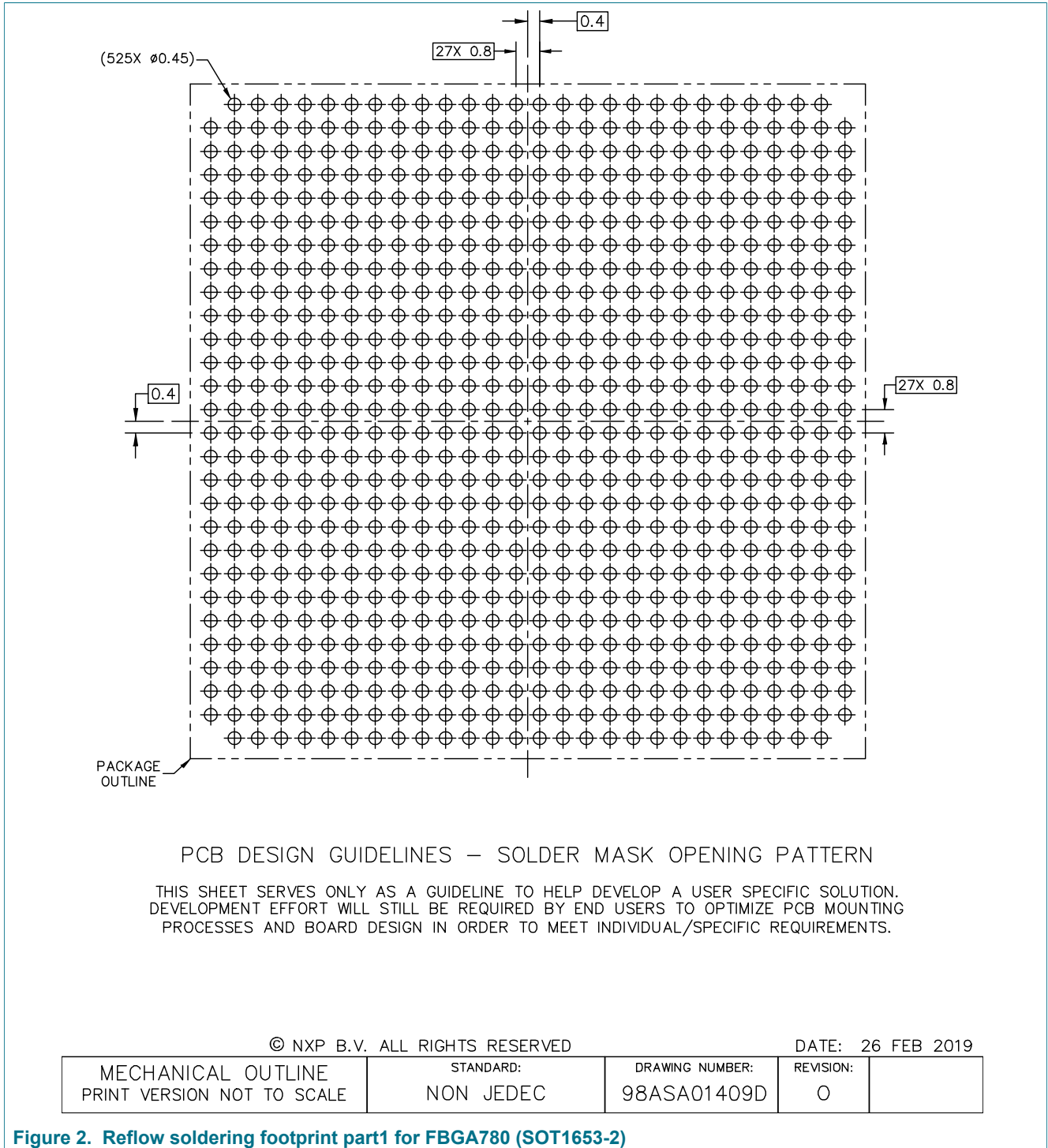
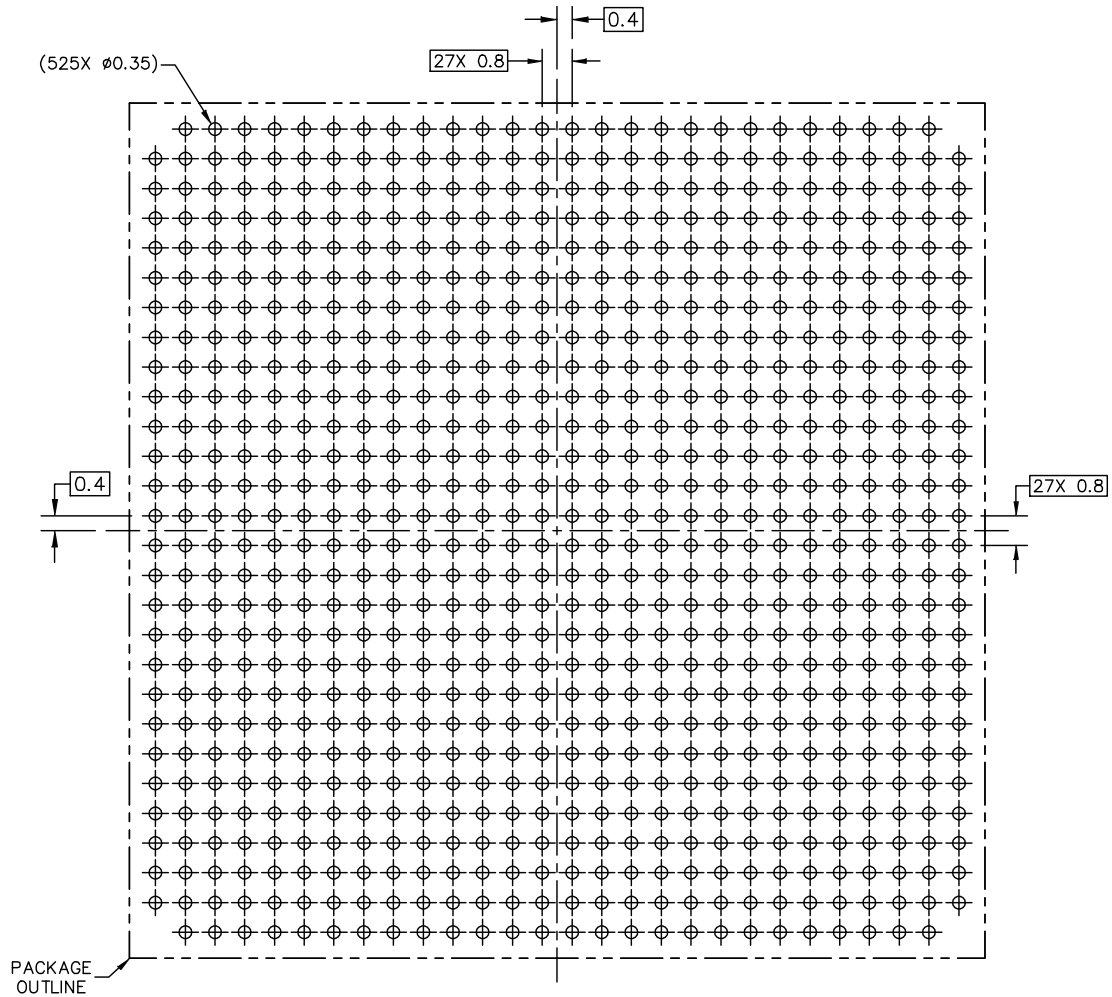


Figure 1. Package outline FBGA780 (SOT1653-2)

3 Soldering



FBGA780, fine-pitch ball grid array package, 780 terminals, 0.8 mm pitch, 23 mm x 23 mm x 2.46 mm body



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DATE: 26 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01409D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for FBGA780 (SOT1653-2)

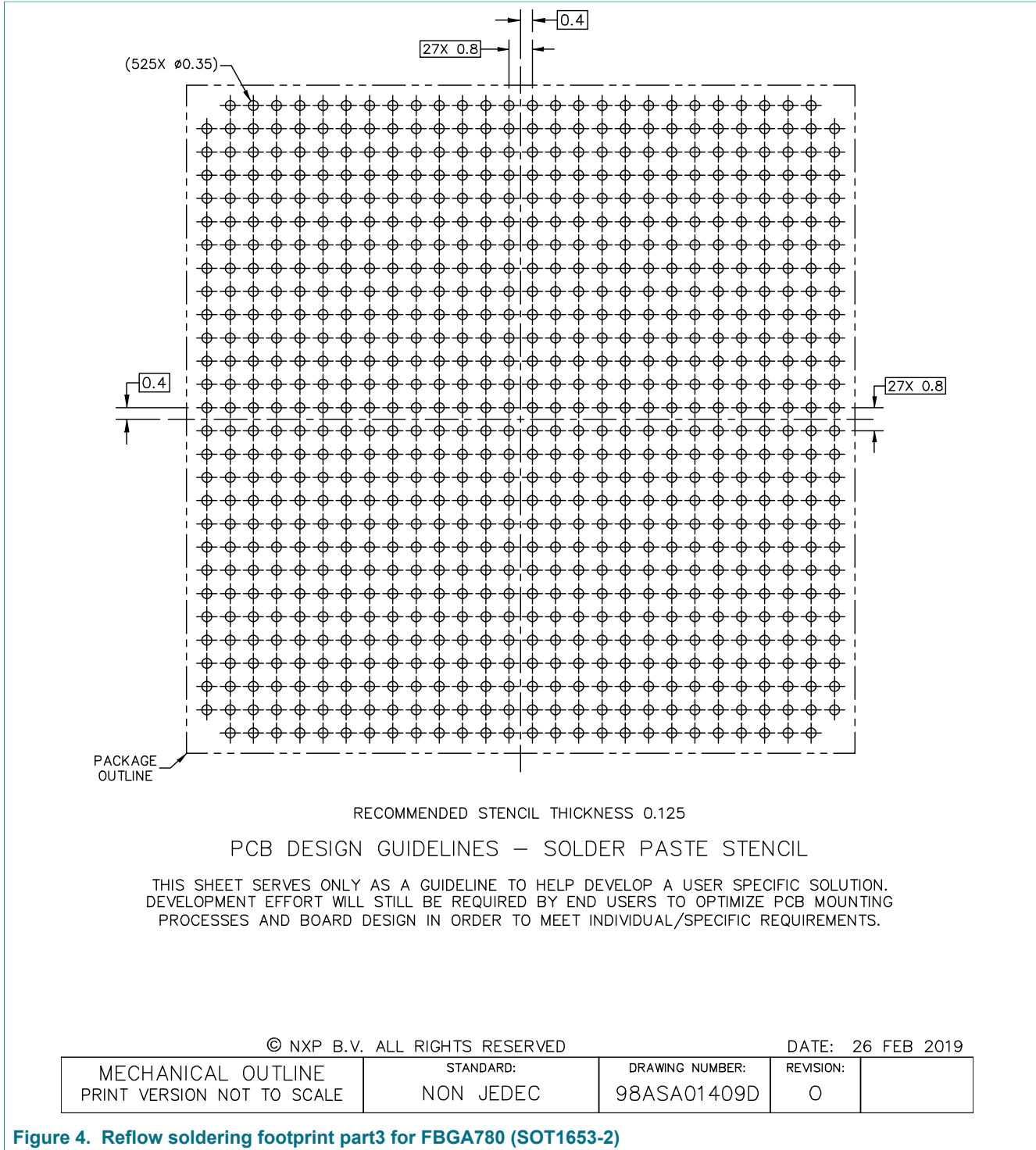


Figure 4. Reflow soldering footprint part3 for FBGA780 (SOT1653-2)

4 Legal information

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